

Material Data Sheet

Varistor

	Multilayer Varistor CT-Type B725xxX* (suffix V9)
Date	13.07.2020
IMDS ID if available	
Version	5.01

Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic	3B	ZnO	88,5	1314-13-2	94	
			Bi2O3	6	1304-76-3		
			Sb2O3	2	1309-64-4		
			Co3O4	1,5	1308-06-1		
			SiO2	1	14808-60-7		
			others*)	1	-		
nner Electrode	Noble Metal	1D7	Ag	100	7440-22-4	1	
Termination	Composite	4D	Ag	90	7440-22-4	4,2	
			Glass frit (boro-silicate)	10			
	Heavy Metal	1C8	Sn	100	7440-31-5	0,5	
	Heavy Metal	1C14	Ni	100	7440-02-0	0,3	
				•	Sum of total	100	•

				Ouin o	i totai	100
sizes [mm]	weight range [g]	material numbers	part numbers			
1.0 x 0.5 x 0.5	0.001 - 0.004	B7259*X*	0402			
1.6 x 0.8 x 0.8	0.004 - 0.007	B7250*X*	0603			
2.0 x 1.25 x 1.1	0.007 - 0.02	B7251*X*	0805			
3.2 x 1.6 x 1.1	0.02 - 0.04	B7252*X*	1206			
3.2 x 2.5 x 2.5	0.04 - 0.1	B7253*X*	1210			
4.5 x 3.2 x 2.2	0.08 - 0.2	B7258*X*	1812			
5.7 x 5.0 x 3.4	0.15 - 0.45	B7254*X*	2220			
Not part of a Product Class						

Contact	Ronner Christoph		Important remarks:				
Division	PPD Q QM		The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906). Traces are				
Address	8530 Deutschlandsberg, AUSTRIA		product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise				
	Tel:	mailto:	regulated.				
	+43 3462 800 2139	functional.ppd-epqm.db@tdk-electronics.tdk.com	2) This Material Data Sheet contains typical values of the respective products set forth				
*) others: .(not declarable or prohibited substances acc. GADSL)			herein. We expressly point out that all values and statements contained herein are based on our				
**) typical mass percentage of substance			best present knowledge and cannot be regarded as binding statements or binding product				
			specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS				
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			WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS				
			AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY				
			REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY				

The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (☑ valid ☐ not valid)

☑ no exemptions;

- □ Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;
- $\begin{tabular}{ll} \square Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 \% lead by weight; \\ \end{tabular}$
- ☐ Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;
- □ Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);
- ☐ Exemption 7 (c)-1: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;
- □ Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;
- Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;
 Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;
- ☐ Other Exemption than above